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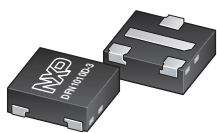
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Team Nexperia



PPTC143/114/124/144EQA series

50 V, 100 mA NPN resistor-equipped transistors

Rev. 1 — 30 October 2015

Product data sheet

1. Product profile

1.1 General description

100 mA NPN Resistor-Equipped Transistor (RET) family in a leadless ultra small DFN1010D-3 (SOT1215) Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

Table 1. Product overview

Type number	R1	R2	Package NXP	PNP complement
PPTC143EQA	4.7 k Ω	4.7 k Ω	DFN1010D-3 (SOT1215)	PDTA143EQA
PPTC114EQA	10 k Ω	10 k Ω		PDTA114EQA
PPTC124EQA	22 k Ω	22 k Ω		PDTA124EQA
PPTC144EQA	47 k Ω	47 k Ω		PDTA144EQA

1.2 Features and benefits

- 100 mA output current capability
- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- Reduced pick and place costs
- Low package height of 0.37 mm
- AEC-Q101 qualified
- Suitable for Automatic Optical Inspection (AOI) of solder joint

1.3 Applications

- Digital applications
- Cost saving alternative for BC847/BC857 series in digital applications
- Controlling IC inputs
- Switching loads

1.4 Quick reference data

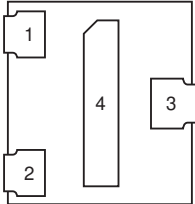
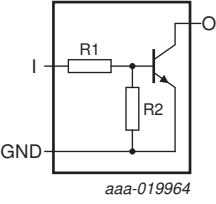
Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CEO}	collector-emitter voltage	open base	-	-	50	V
I _O	output current		-	-	100	mA



2. Pinning information

Table 3. Pinning

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	I	input (base)	 <p>Transparent top view</p>	 <p>aaa-019964</p>
2	GND	GND (emitter)		
3	O	output (collector)		
4	O	output (collector)		

3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
PDTC143EQA	DFN1010D-3	plastic thermal enhanced ultra thin small outline package; no leads; 3 terminals; body: 1.1 × 1.0 × 0.37 mm	SOT1215
PDTC114EQA			
PDTC124EQA			
PDTC144EQA			

4. Marking

Table 5. Marking codes

Type number	Marking code
PDTC143EQA	10 10 01
PDTC114EQA	11 01 10
PDTC124EQA	10 11 01
PDTC144EQA	10 01 10

4.1 Binary marking code description

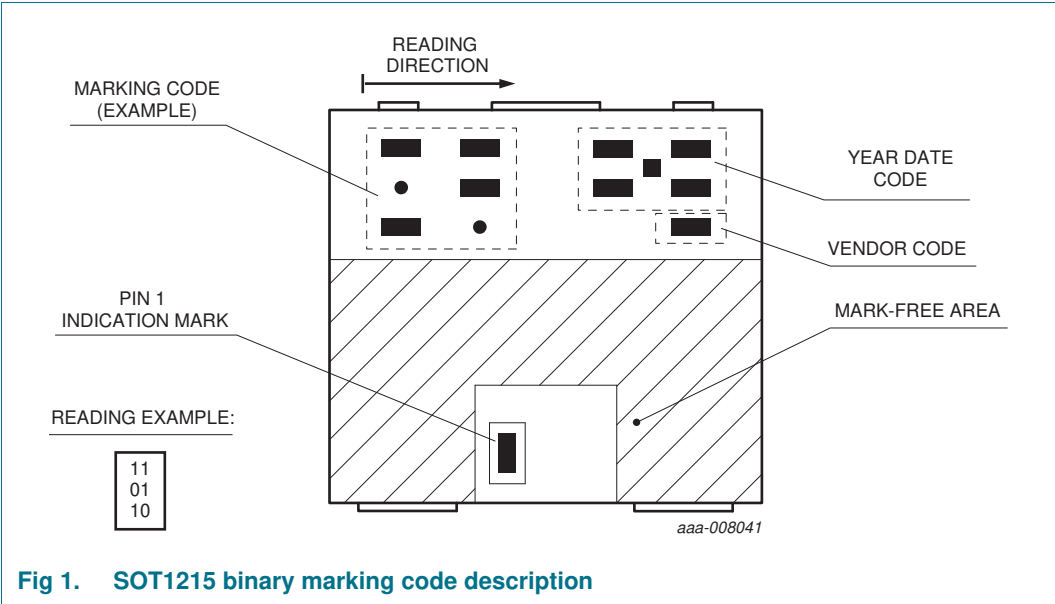


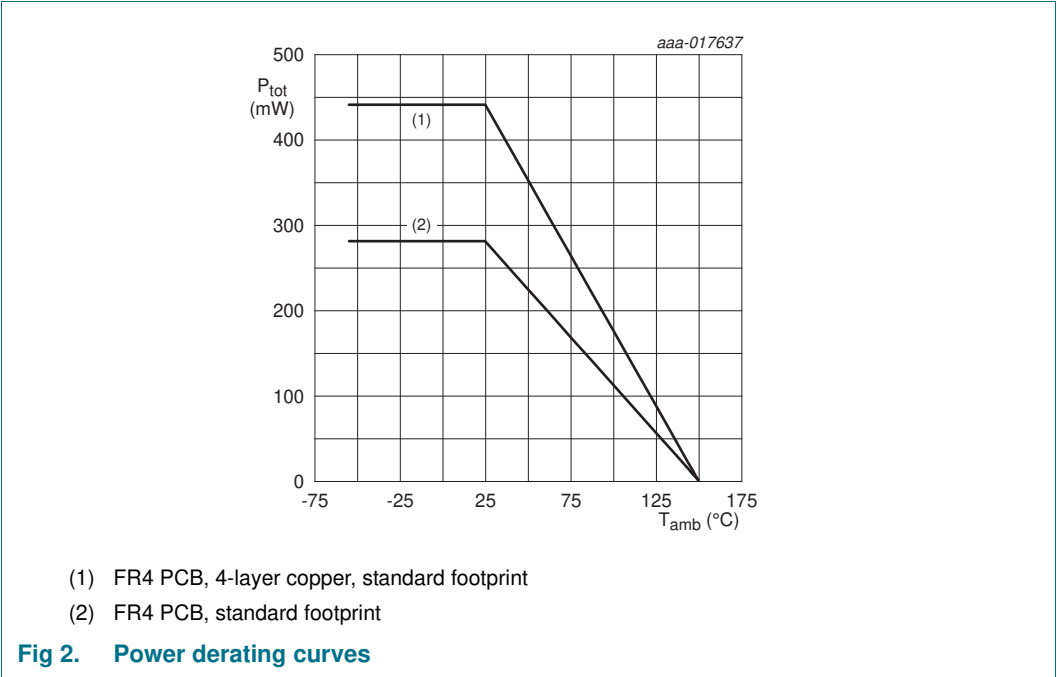
Fig 1. SOT1215 binary marking code description

5. Limiting values

Table 6. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CBO}	collector-base voltage	open emitter	-	50	V
V _{CEO}	collector-emitter voltage	open base	-	50	V
V _{EBO}	emitter-base voltage		-	10	V
V _I	input voltage				
	PDTC143EQA		-10	+30	V
	PDTC114EQA		-10	+40	V
	PDTC124EQA		-10	+40	V
	PDTC144EQA		-10	+40	V
I _O	output current		-	100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C	[1]	280	mW
			[2]	440	mW
T _j	junction temperature		-	150	°C
T _{amb}	ambient temperature		-55	+150	°C
T _{stg}	storage temperature		-65	+150	°C

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.

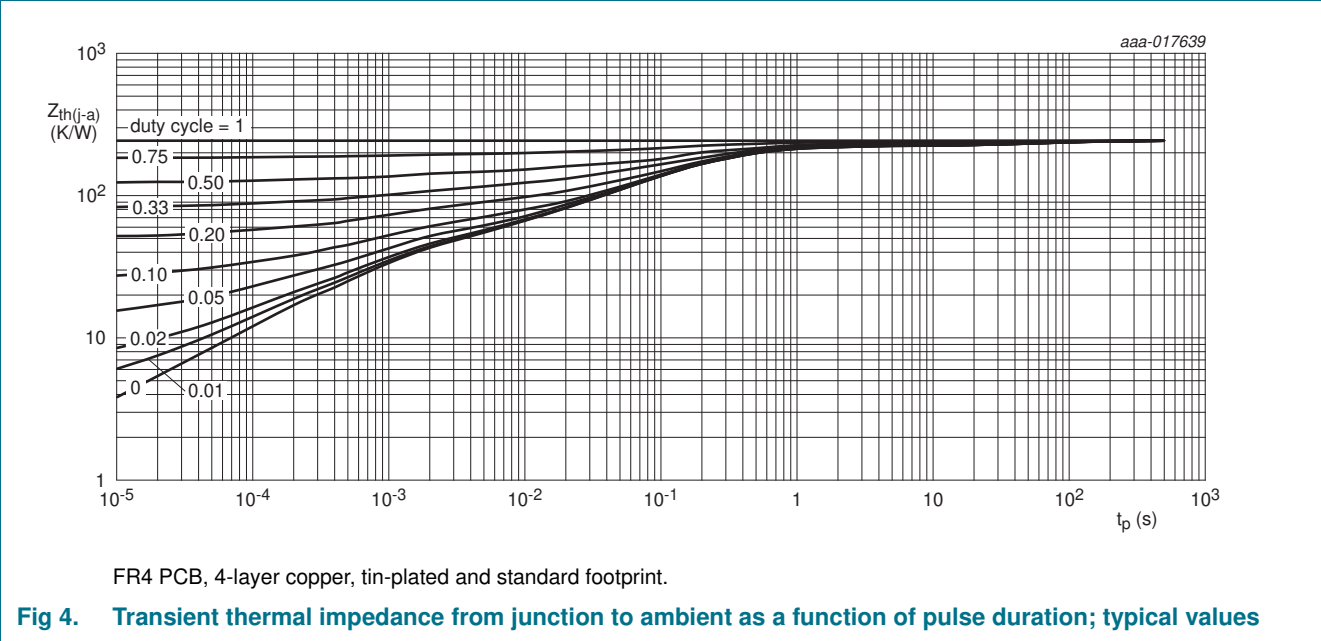
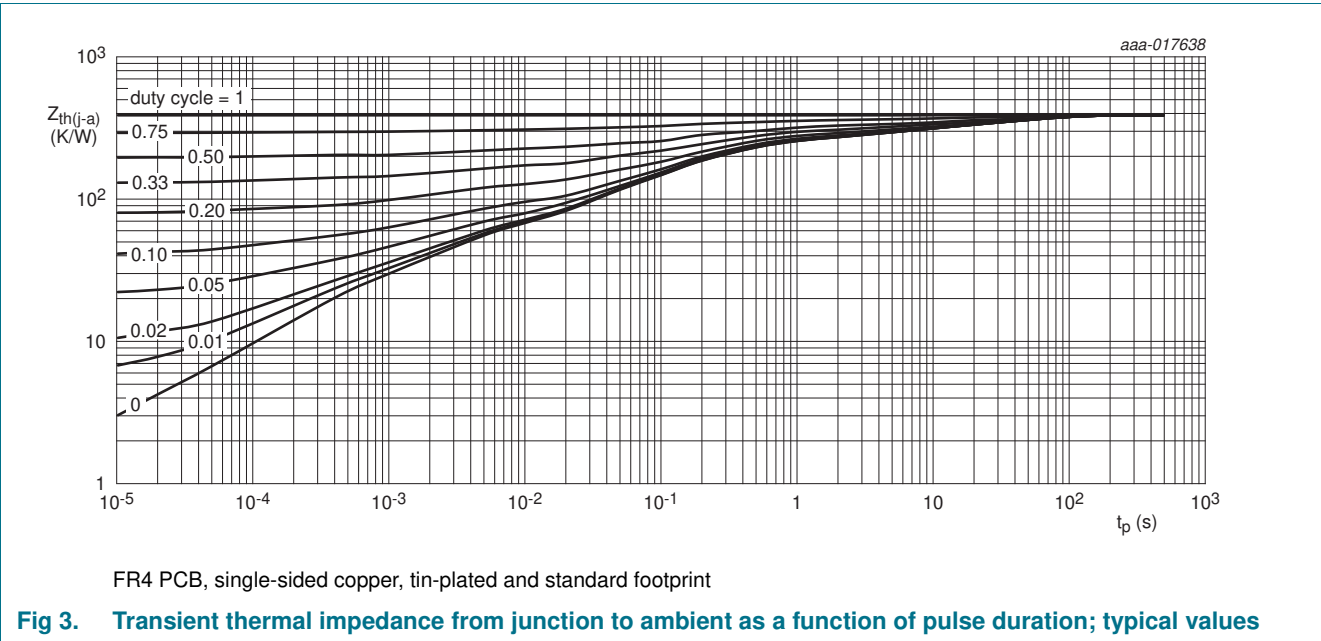


6. Thermal characteristics

Table 7. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	446	K/W
			[2]	-	284	K/W

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [2] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.



7. Characteristics

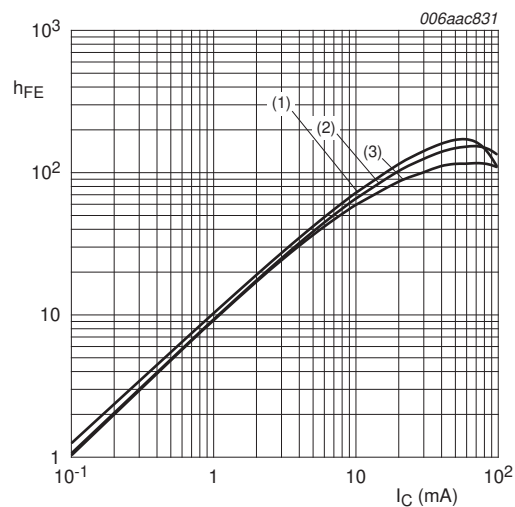
Table 8. Characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	$V_{CB} = 50\text{ V}; I_E = 0\text{ A}$	-	-	100	nA
I_{CEO}	collector-emitter cut-off current	$V_{CE} = 30\text{ V}; I_B = 0\text{ A}$	-	-	1	μA
		$V_{CE} = 30\text{ V}; I_B = 0\text{ A}; T_j = 150\text{ }^{\circ}\text{C}$	-	-	5	μA
I_{EBO}	emitter-base cut-off current					
	PDTC143EQA	$V_{EB} = 5\text{ V}; I_C = 0\text{ A}$	-	-	900	μA
	PDTC114EQA		-	-	400	μA
	PDTC124EQA		-	-	180	μA
	PDTC144EQA		-	-	90	μA
h_{FE}	DC current gain					
	PDTC143EQA	$V_{CE} = 5\text{ V}; I_C = 10\text{ mA}$	30	-	-	
	PDTC114EQA	$V_{CE} = 5\text{ V}; I_C = 5\text{ mA}$	30	-	-	
	PDTC124EQA		60	-	-	
	PDTC144EQA		80	-	-	
V_{CEsat}	collector-emitter saturation voltage	$I_C = 10\text{ mA}; I_B = 0.5\text{ mA}$	-	-	150	mV
$V_{I(off)}$	off-state input voltage					
	PDTC143EQA	$V_{CE} = 5\text{ V}; I_C = 100\text{ }\mu\text{A}$	-	1.1	0.5	V
	PDTC114EQA		-	1.1	0.8	V
	PDTC124EQA		-	1.1	0.8	V
	PDTC144EQA		-	1.2	0.8	V
$V_{I(on)}$	on-state input voltage					
	PDTC143EQA	$V_{CE} = 0.3\text{ V}; I_C = 20\text{ mA}$	2.5	1.9	-	V
	PDTC114EQA	$V_{CE} = 0.3\text{ V}; I_C = 10\text{ mA}$	2.5	1.8	-	V
	PDTC124EQA	$V_{CE} = 0.3\text{ V}; I_C = 5\text{ mA}$	2.5	1.7	-	V
	PDTC144EQA	$V_{CE} = 0.3\text{ V}; I_C = 2\text{ mA}$	3	1.6	-	V
R1	bias resistor 1 (input)	[1]				
	PDTC143EQA		3.3	4.7	6.1	k Ω
	PDTC114EQA		7	10	13	k Ω
	PDTC124EQA		15.4	22	28.6	k Ω
	PDTC144EQA		33	47	61	k Ω
R2/R1	bias resistor ratio	[1]	0.8	1	1.2	
C_c	collector capacitance	$V_{CB} = 10\text{ V}; I_E = I_C = 0\text{ A}; f = 1\text{ MHz}$	-	-	2.5	pF
f_T	transition frequency	$V_{CE} = 5\text{ V}; I_C = 10\text{ mA}; f = 100\text{ MHz}$ [2]	-	230	-	MHz

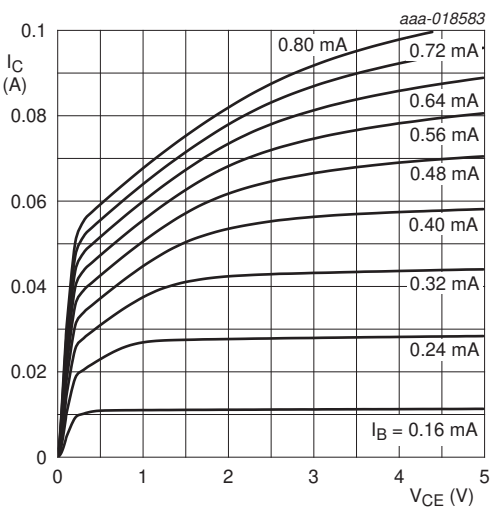
[1] See [Section 8 "Test information"](#) for resistor calculation and test conditions.

[2] Characteristics of built-in transistor.



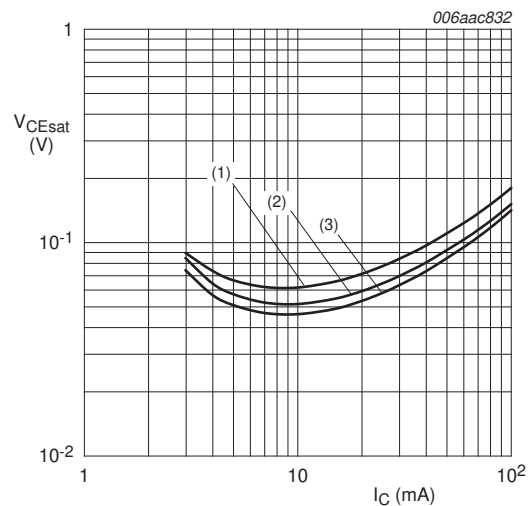
$V_{CE} = 5\text{ V}$
(1) $T_{amb} = 100^\circ\text{C}$
(2) $T_{amb} = 25^\circ\text{C}$
(3) $T_{amb} = -40^\circ\text{C}$

Fig 5. PDTC143EQA: DC current gain as a function of collector current; typical values



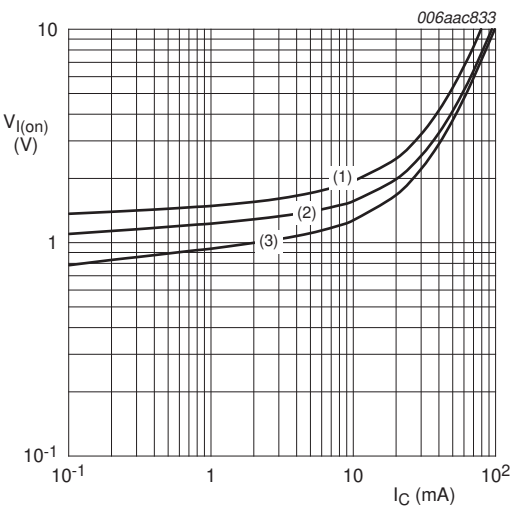
$T_{amb} = 25^\circ\text{C}$

Fig 6. PDTC143EQA: Collector current as a function of collector-emitter voltage; typical values



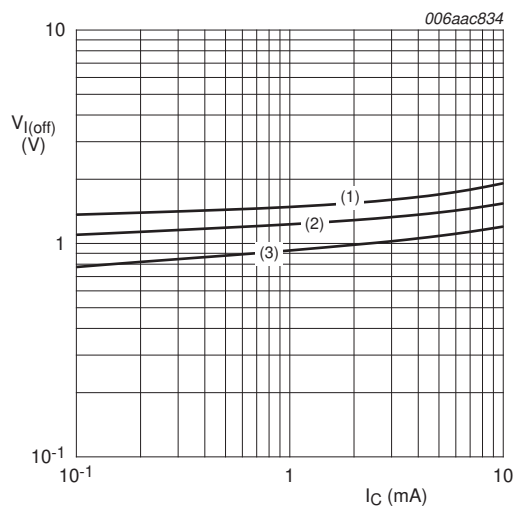
$I_C/I_B = 20$
(1) $T_{amb} = 100^\circ\text{C}$
(2) $T_{amb} = 25^\circ\text{C}$
(3) $T_{amb} = -40^\circ\text{C}$

Fig 7. PDTC143EQA: Collector-emitter saturation voltage as a function of collector current; typical values



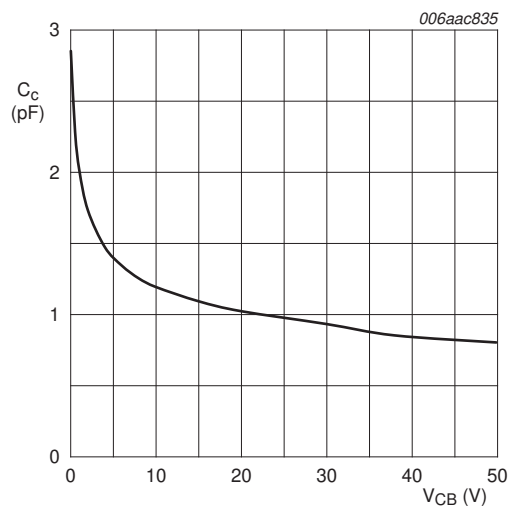
$V_{CE} = 0.3\text{ V}$
(1) $T_{amb} = -40^\circ\text{C}$
(2) $T_{amb} = 25^\circ\text{C}$
(3) $T_{amb} = 100^\circ\text{C}$

Fig 8. PDTC143EQA: On-state input voltage as a function of collector current; typical values



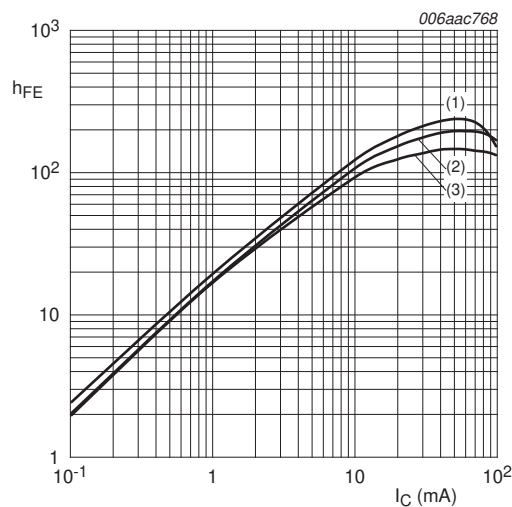
$V_{CE} = 5\text{ V}$
(1) $T_{amb} = -40\text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
(3) $T_{amb} = 100\text{ }^{\circ}\text{C}$

Fig 9. PDTC143EQA: Off-state input voltage as a function of collector current; typical values



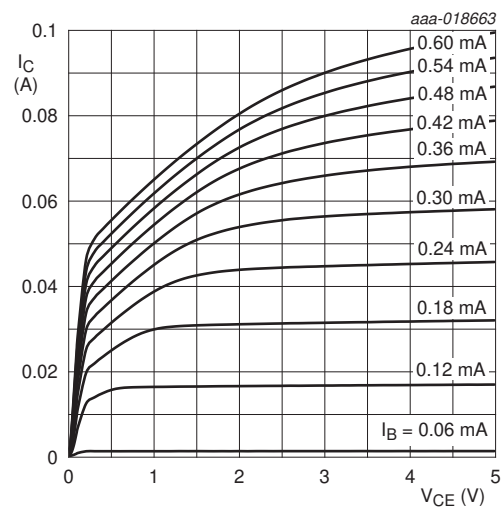
$f = 1\text{ MHz}; T_{amb} = 25\text{ }^{\circ}\text{C}$

Fig 10. PDTC143EQA: Collector capacitance as a function of collector-base voltage; typical values



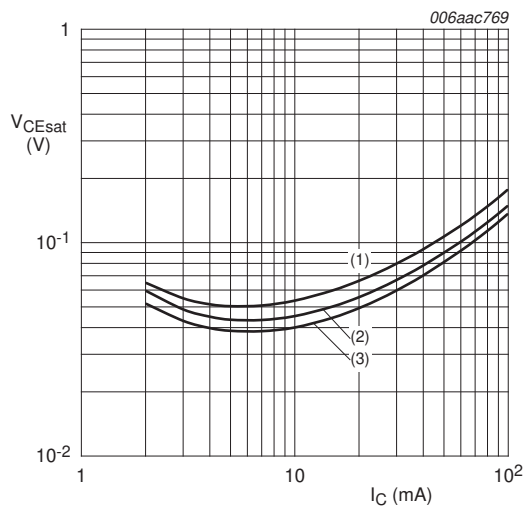
- $V_{CE} = 5\text{ V}$
- (1) $T_{amb} = 100\text{ }^{\circ}\text{C}$
 - (2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
 - (3) $T_{amb} = -40\text{ }^{\circ}\text{C}$

Fig 11. PDTC114EQA: DC current gain as a function of collector current; typical values



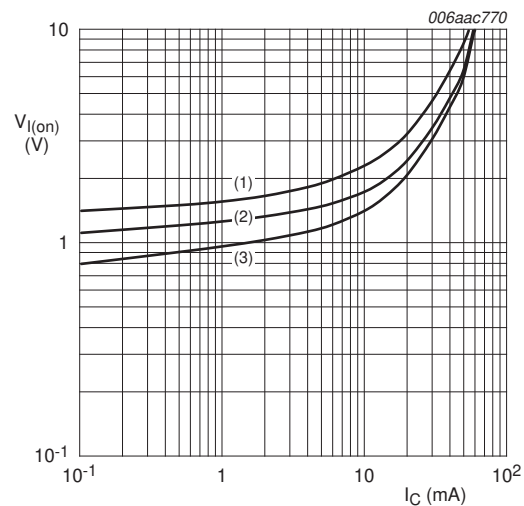
$T_{amb} = 25\text{ }^{\circ}\text{C}$

Fig 12. PDTC114EQA: Collector current as a function of collector-emitter voltage; typical values



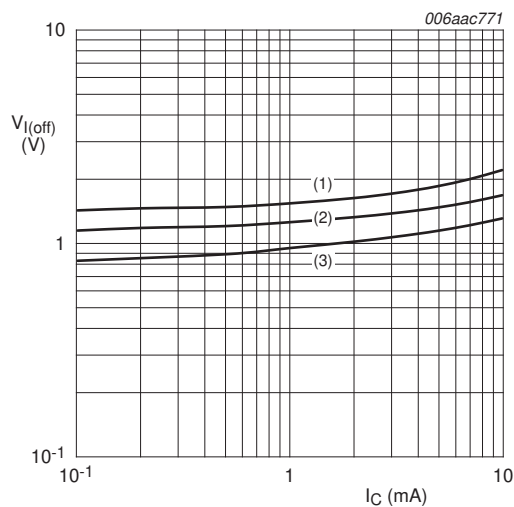
- $I_C/I_B = 20$
- (1) $T_{amb} = 100\text{ }^{\circ}\text{C}$
 - (2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
 - (3) $T_{amb} = -40\text{ }^{\circ}\text{C}$

Fig 13. PDTC114EQA: Collector-emitter saturation voltage as a function of collector current; typical values



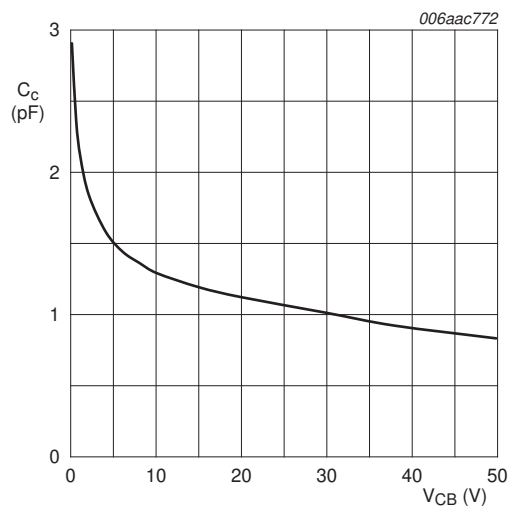
- $V_{CE} = 0.3\text{ V}$
- (1) $T_{amb} = -40\text{ }^{\circ}\text{C}$
 - (2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
 - (3) $T_{amb} = 100\text{ }^{\circ}\text{C}$

Fig 14. PDTC114EQA: On-state input voltage as a function of collector current; typical values



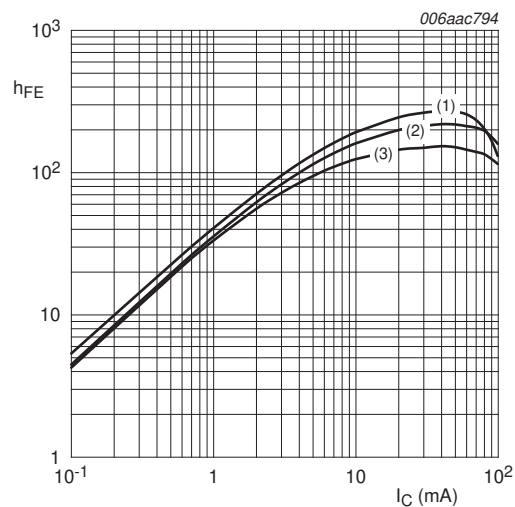
- $V_{CE} = 5\text{ V}$
- (1) $T_{amb} = -40\text{ }^{\circ}\text{C}$
 - (2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
 - (3) $T_{amb} = 100\text{ }^{\circ}\text{C}$

Fig 15. PDTC114EQA: Off-state input voltage as a function of collector current; typical values



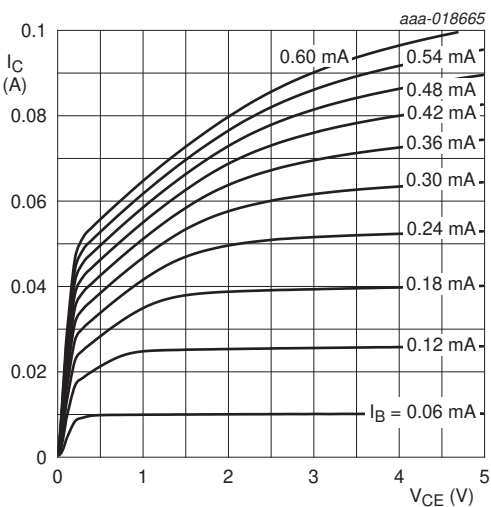
$f = 1\text{ MHz}; T_{amb} = 25\text{ }^{\circ}\text{C}$

Fig 16. PDTC114EQA: Collector capacitance as a function of collector-base voltage; typical values



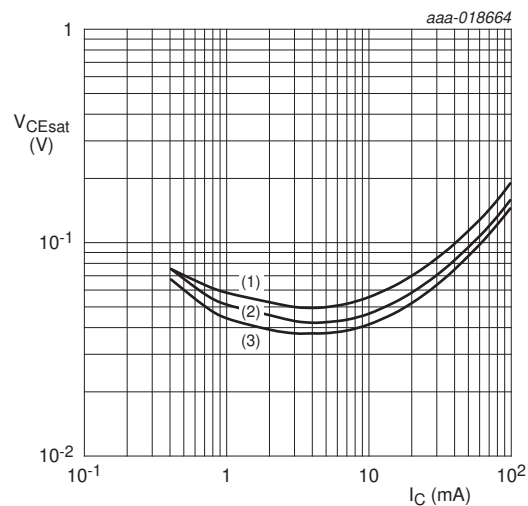
$V_{CE} = 5\text{ V}$
(1) $T_{amb} = 100^\circ\text{C}$
(2) $T_{amb} = 25^\circ\text{C}$
(3) $T_{amb} = -40^\circ\text{C}$

Fig 17. PDTC124EQA: DC current gain as a function of collector current; typical values



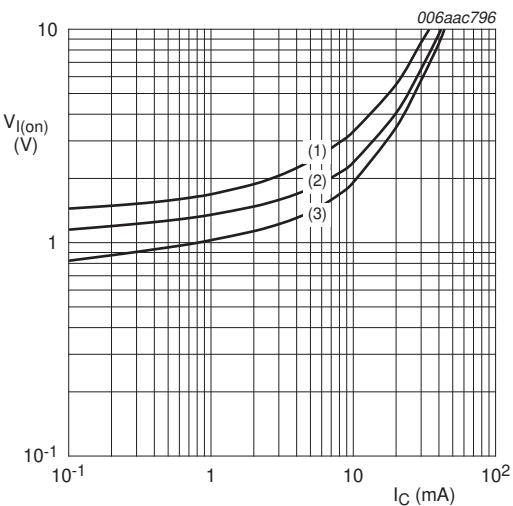
$T_{amb} = 25^\circ\text{C}$

Fig 18. PDTC124EQA: Collector current as a function of collector-emitter voltage; typical values



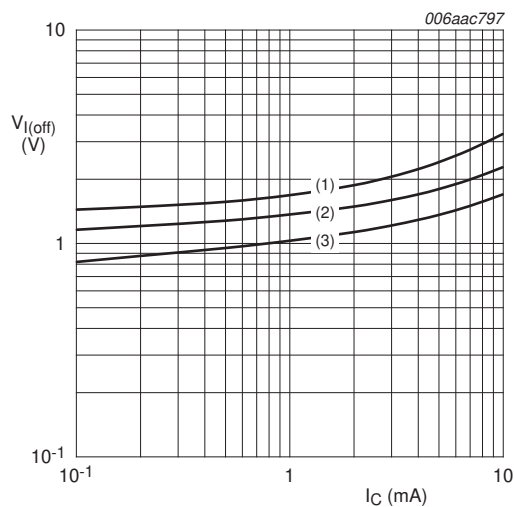
$I_C/I_B = 20$
(1) $T_{amb} = 100^\circ\text{C}$
(2) $T_{amb} = 25^\circ\text{C}$
(3) $T_{amb} = -40^\circ\text{C}$

Fig 19. PDTC124EQA: Collector-emitter saturation voltage as a function of collector current; typical values



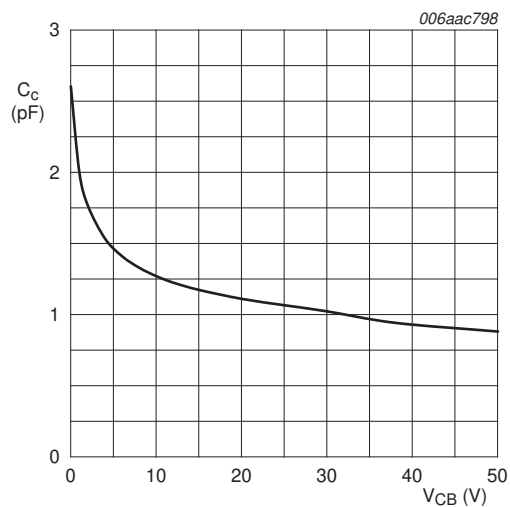
$V_{CE} = 0.3\text{ V}$
(1) $T_{amb} = -40^\circ\text{C}$
(2) $T_{amb} = 25^\circ\text{C}$
(3) $T_{amb} = 100^\circ\text{C}$

Fig 20. PDTC124EQA: On-state input voltage as a function of collector current; typical values



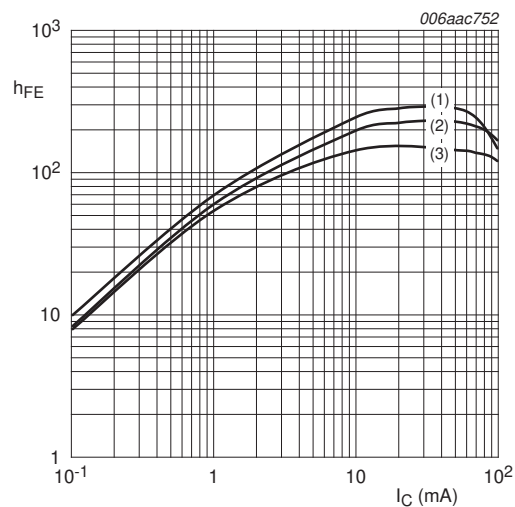
- $V_{CE} = 5\text{ V}$
- (1) $T_{amb} = -40^\circ\text{C}$
 - (2) $T_{amb} = 25^\circ\text{C}$
 - (3) $T_{amb} = 100^\circ\text{C}$

Fig 21. PDTC124EQA: Off-state input voltage as a function of collector current; typical values



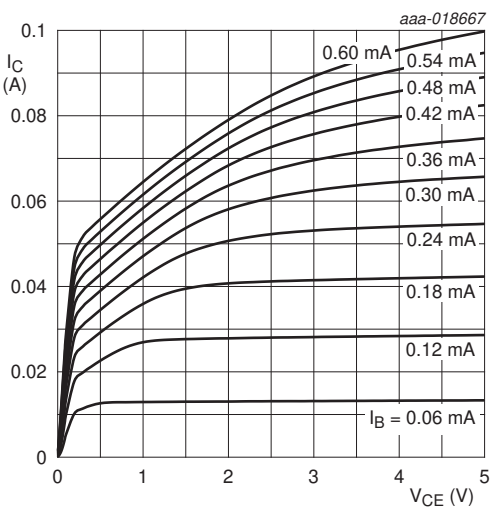
$f = 1\text{ MHz}; T_{amb} = 25^\circ\text{C}$

Fig 22. PDTC124EQA: Collector capacitance as a function of collector-base voltage; typical values



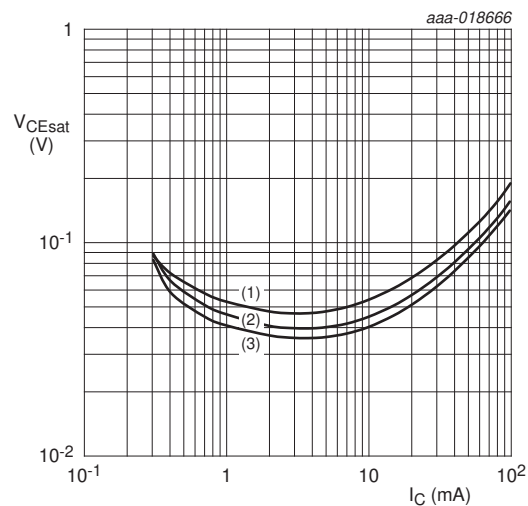
$V_{CE} = 5\text{ V}$
(1) $T_{amb} = 100\text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
(3) $T_{amb} = -40\text{ }^{\circ}\text{C}$

Fig 23. PDTC144EQA: DC current gain as a function of collector current; typical values



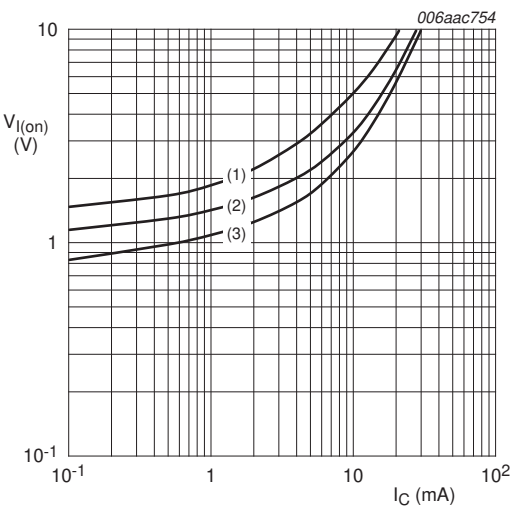
$T_{amb} = 25\text{ }^{\circ}\text{C}$

Fig 24. PDTC144EQA: Collector current as a function of collector-emitter voltage; typical values



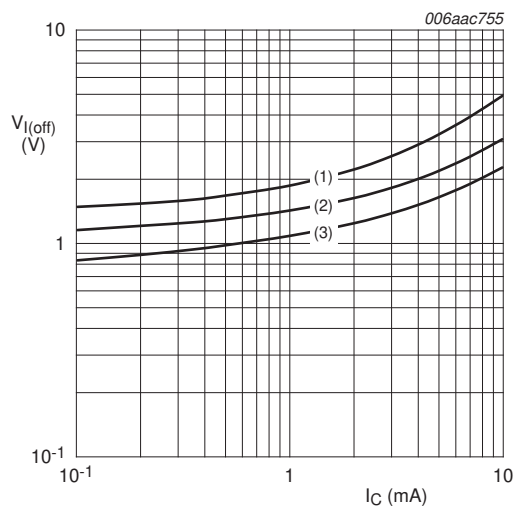
$I_C/I_B = 20$
(1) $T_{amb} = 100\text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
(3) $T_{amb} = -40\text{ }^{\circ}\text{C}$

Fig 25. PDTC144EQA: Collector-emitter saturation voltage as a function of collector current; typical values



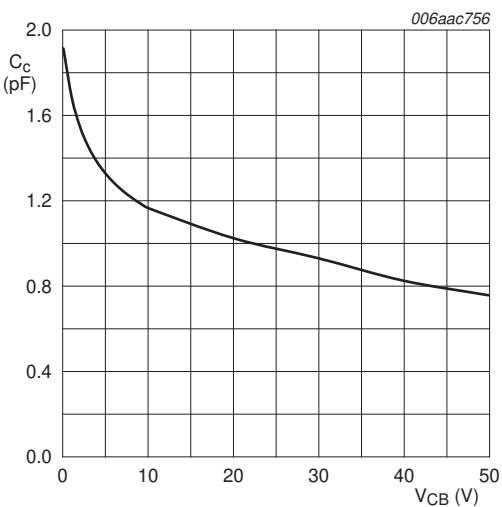
$V_{CE} = 0.3\text{ V}$
(1) $T_{amb} = -40\text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
(3) $T_{amb} = 100\text{ }^{\circ}\text{C}$

Fig 26. PDTC144EQA: On-state input voltage as a function of collector current; typical values



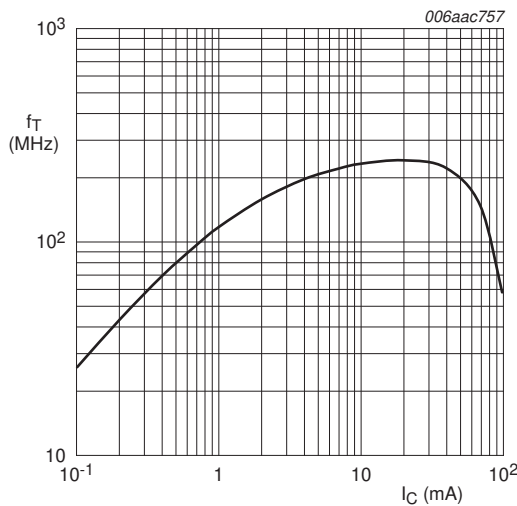
- $V_{CE} = 5\text{ V}$
- (1) $T_{amb} = -40^\circ\text{C}$
 - (2) $T_{amb} = 25^\circ\text{C}$
 - (3) $T_{amb} = 100^\circ\text{C}$

Fig 27. PDTC144EQA: Off-state input voltage as a function of collector current; typical values



$f = 1\text{ MHz}; T_{amb} = 25^\circ\text{C}$

Fig 28. PDTC144EQA: Collector capacitance as a function of collector-base voltage; typical values



$V_{CE} = 5\text{ V}; T_{amb} = 25^\circ\text{C}$

Fig 29. Transition frequency as a function of collector current; typical values of built-in transistor

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

8.2 Resistor calculation

- Calculation of bias resistor 1 (R1):

$$R1 = \frac{V(I_{I2}) - V(I_{I1})}{I_{I2} - I_{I1}}$$

- Calculation of bias resistor ratio (R2/R1):

$$\frac{R2}{R1} = \frac{V(I_{I4}) - V(I_{I3})}{R1 \cdot (I_{I4} - I_{I3})} - 1$$

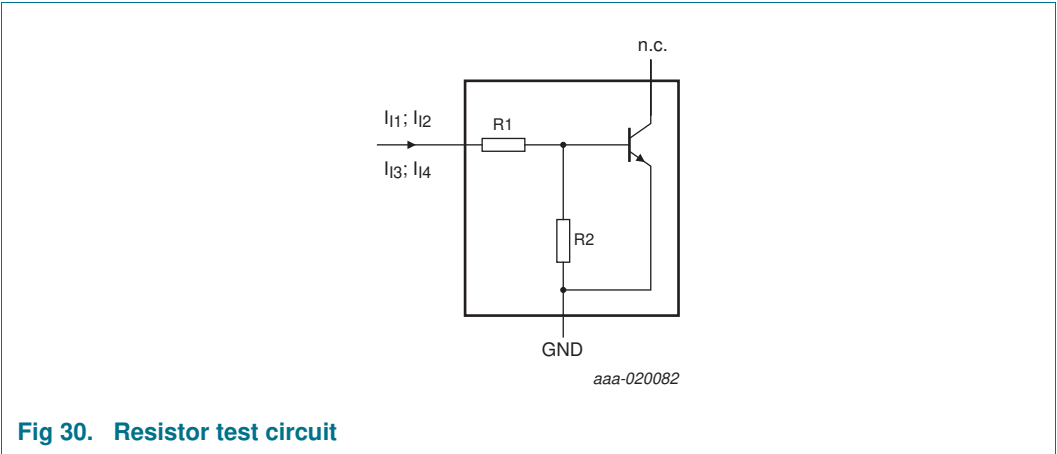


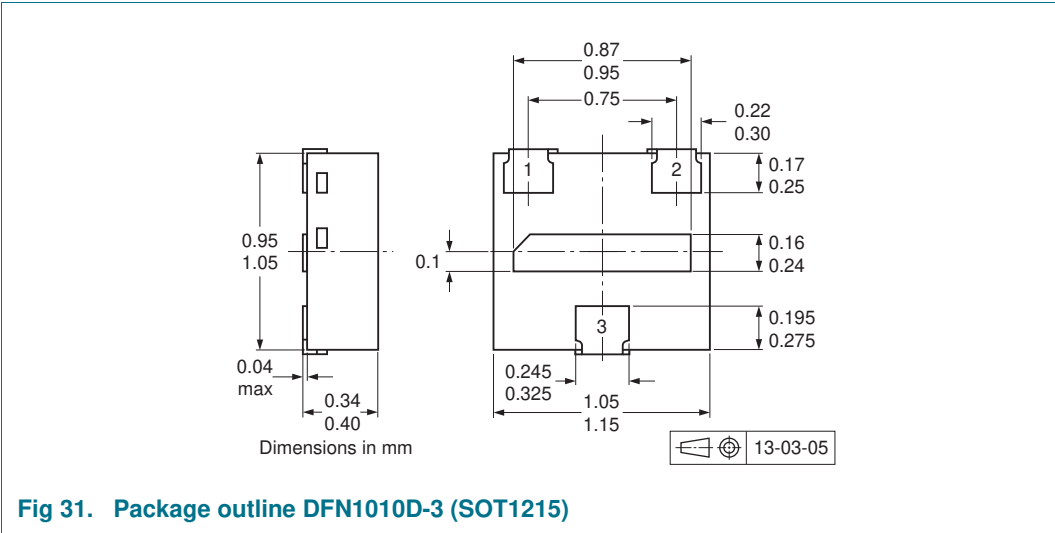
Fig 30. Resistor test circuit

8.3 Resistor test conditions

Table 9. Resistor test conditions

Type number	R1 (kΩ)	R2 (kΩ)	Test conditions			
			I _{I1}	I _{I2}	I _{I3}	I _{I4}
PDTC143EQA	4.7	4.7	600 μA	700 μA	-600 μA	-700 μA
PDTC114EQA	10	10	350 μA	450 μA	-350 μA	-450 μA
PDTC124EQA	22	22	150 μA	230 μA	-150 μA	-230 μA
PDTC144EQA	47	47	55 μA	105 μA	-55 μA	-105 μA

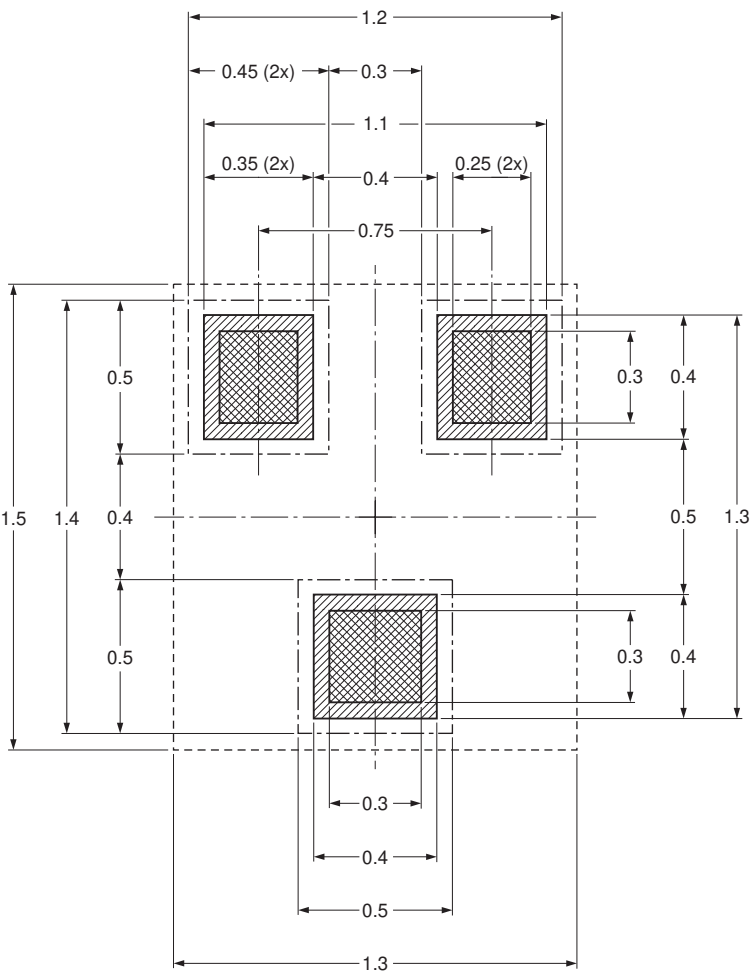
9. Package outline







10. Soldering

Footprint information for reflow soldering of DFN1010D-3 package

SOT1215



-  solder land
-  solder land plus solder paste
-  occupied area
-  solder resist

Dimensions in mm

Issue date ~~12-11-23~~
13-03-06

sot1215_fr

Fig 32. Reflow soldering footprint DFN1010D-3 (SOT1215)

11. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PDTC143_114_124_144EQA_SER v.1	20151030	Product data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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